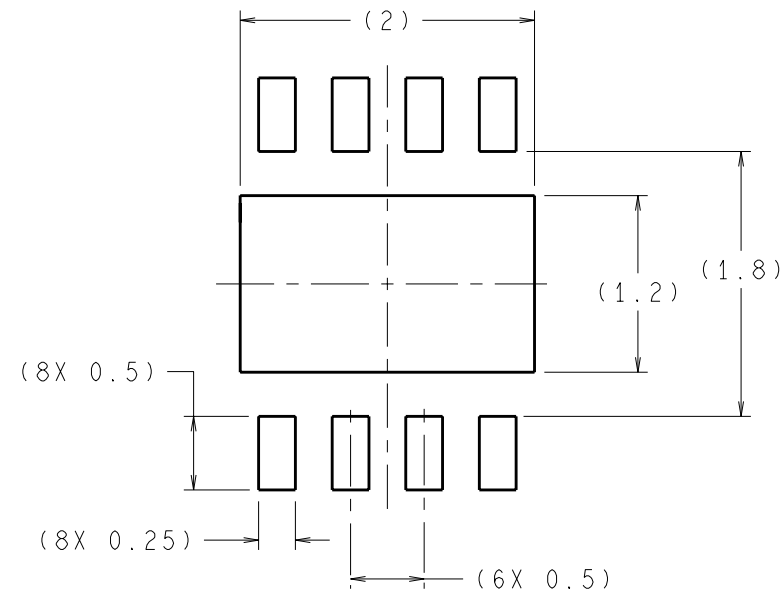
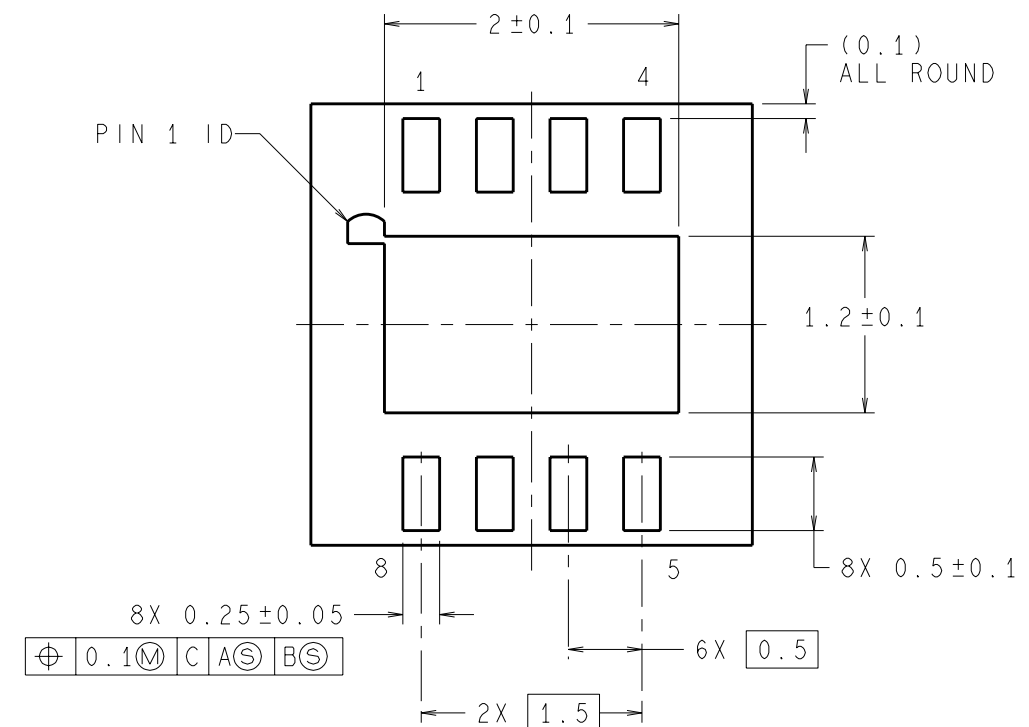
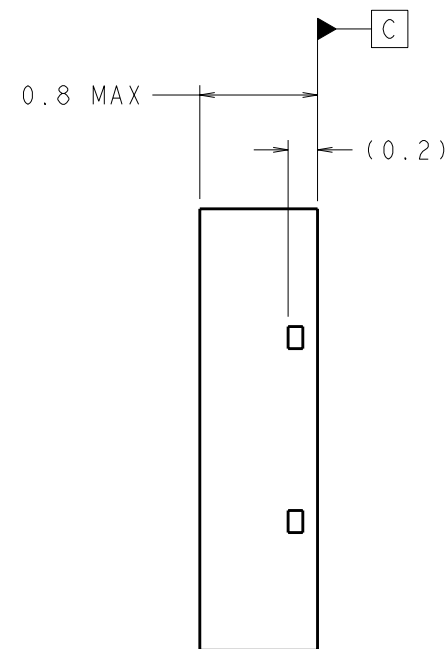
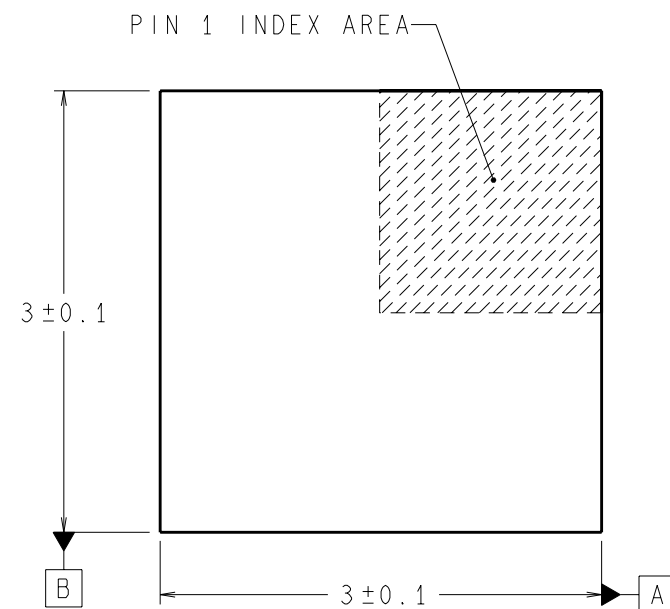


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	122	05/30/2000	SN/TL/AL
B	CHG EXPOSED DAP LENGTH : 2.0 WAS 1.8; APPLY JEDEC REGISTRATION TO NOTE 2	366	10/05/2001	TE/TL/SN



DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATION WITH PKG SOLDER PADS



NOTES: UNLESS OTHERWISE SPECIFIED.

- STANDARD LEAD FINISH TO BE 5.08 MICROMETERS MINIMUM LEAD/TIN (SOLDER) ON COPPER.
- REFERENCE JEDEC REGISTRATION MO-229, VARIATION WEED-1.

APPROVALS	DATE	National Semiconductor			
DRAWN N. SANTHIRAN & TL	05/30/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DFTG. CHK. THANH LEQUANG	10/05/2001	LLP, PLASTIC, DUAL, 3 X 3 X 0.75 mm BODY, 8 LD, 0.5 mm PITCH			
ENGR. CHK. N. SANTHIRAN	10/05/2001				
		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-LDA08A	REV B
		FORMERLY: ***		SHEET 1 of 1	